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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc621t-04e-so

1.0 GENERAL DESCRIPTION

The PIC16C62X devices are 18 and 20-Pin ROM/ EPROM-based members of the versatile PICmicro® family of low cost, high performance, CMOS, fully-static, 8-bit microcontrollers.

All PICmicro microcontrollers employ an advanced RISC architecture. The PIC16C62X devices have enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two-stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches (which require two cycles). A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16C62X microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The PIC16C620A, PIC16C621A and PIC16CR620A have 96 bytes of RAM. The PIC16C622(A) has 128 bytes of RAM. Each device has 13 I/O pins and an 8-bit timer/counter with an 8-bit programmable prescaler. In addition, the PIC16C62X adds two analog comparators with a programmable on-chip voltage reference module. The comparator module is ideally suited for applications requiring a low cost analog interface (e.g., battery chargers, threshold detectors, white goods controllers, etc).

PIC16C62X devices have special features to reduce external components, thus reducing system cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (Power-down) mode offers power savings. The user can wake-up the chip from SLEEP through several external and internal interrupts and RESET.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock-up.

A UV-erasable Cerdip-packaged version is ideal for code development while the cost effective One-Time-Programmable (OTP) version is suitable for production in any volume.

Table 1-1 shows the features of the PIC16C62X mid-range microcontroller families.

A simplified block diagram of the PIC16C62X is shown in Figure 3-1.

The PIC16C62X series fits perfectly in applications ranging from battery chargers to low power remote sensors. The EPROM technology makes

customization of application programs (detection levels, pulse generation, timers, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low cost, low power, high performance, ease of use and I/O flexibility make the PIC16C62X very versatile.

1.1 Family and Upward Compatibility

Those users familiar with the PIC16C5X family of microcontrollers will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to PIC16C62X family of devices (Appendix B). The PIC16C62X family fills the niche for users wanting to migrate up from the PIC16C5X family and not needing various peripheral features of other members of the PIC16XX mid-range microcontroller family.

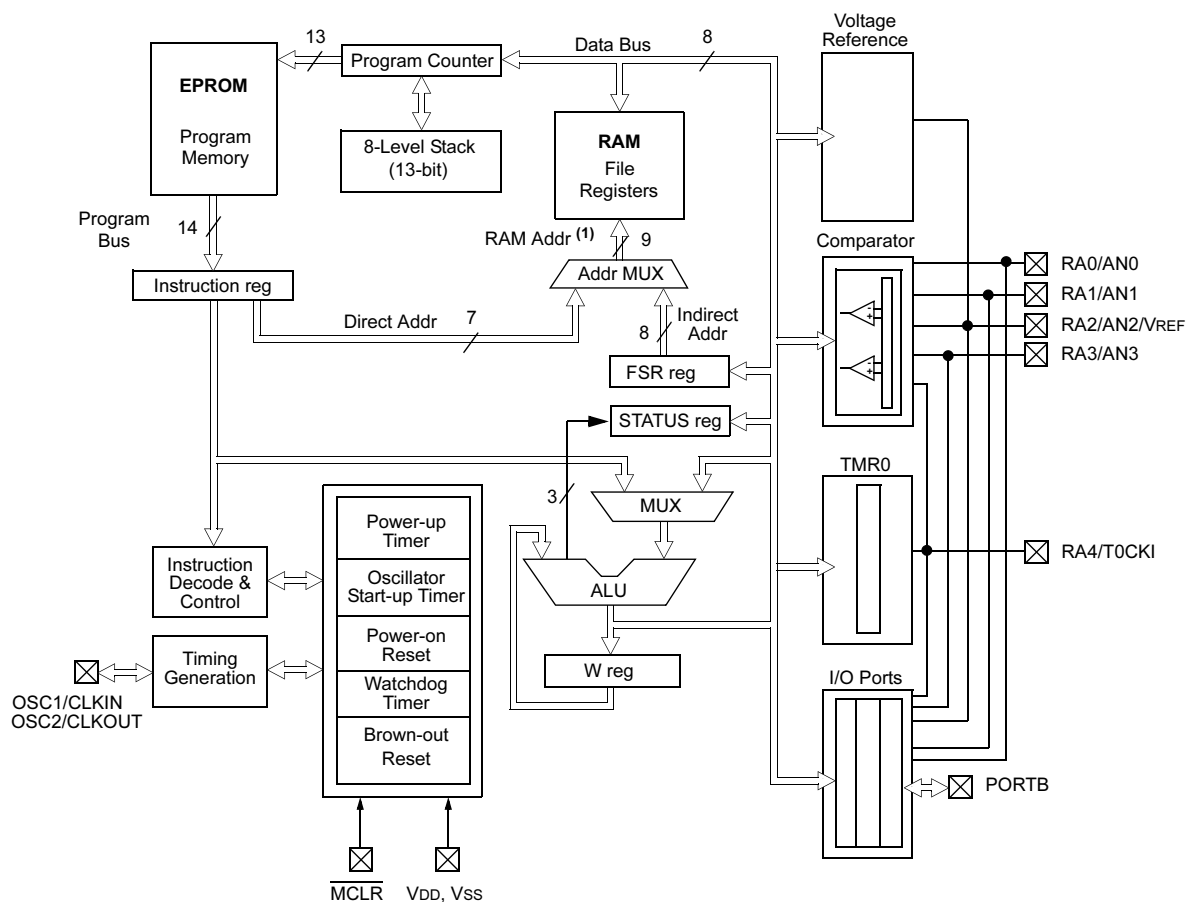
1.2 Development Support

The PIC16C62X family is supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a low cost development programmer and a full-featured programmer. Third Party "C" compilers are also available.

PIC16C62X

FIGURE 3-1: BLOCK DIAGRAM

Device	Program Memory	Data Memory (RAM)
PIC16C620	512 x 14	80 x 8
PIC16C620A	512 x 14	96 x 8
PIC16CR620A	512 x 14	96 x 8
PIC16C621	1K x 14	80 x 8
PIC16C621A	1K x 14	96 x 8
PIC16C622	2K x 14	128 x 8
PIC16C622A	2K x 14	128 x 8



Note 1: Higher order bits are from the STATUS register.

PIC16C62X

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

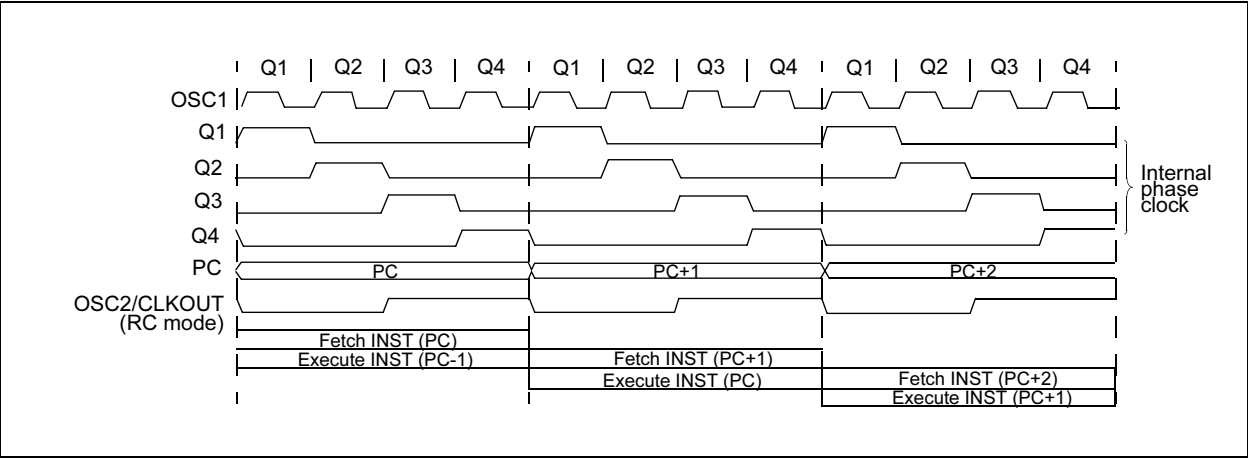
3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

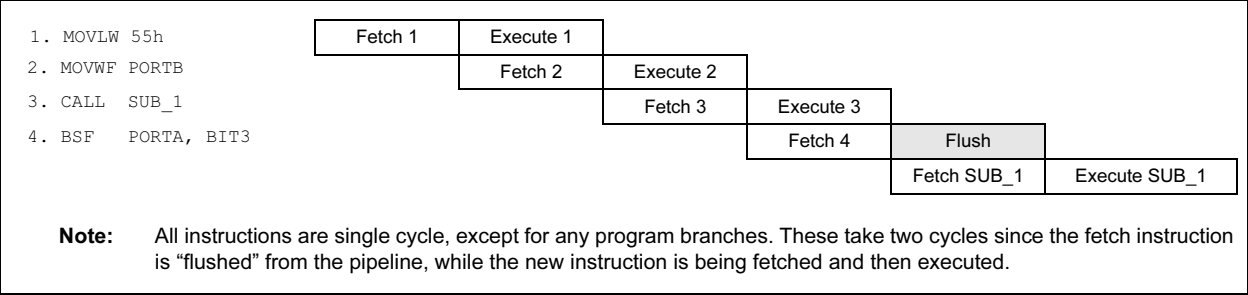
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



PIC16C62X

FIGURE 4-6: DATA MEMORY MAP FOR THE PIC16C620A/CR620A/621A

File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h	General Purpose Register		A0h
6Fh			F0h
70h	General Purpose Register	Accesses 70h-7Fh	F0h
7Fh			FFh
Bank 0		Bank 1	

☐ Unimplemented data memory locations, read as '0'.
Note 1: Not a physical register.

FIGURE 4-7: DATA MEMORY MAP FOR THE PIC16C622A

File Address			File Address
00h	INDF ⁽¹⁾	INDF ⁽¹⁾	80h
01h	TMR0	OPTION	81h
02h	PCL	PCL	82h
03h	STATUS	STATUS	83h
04h	FSR	FSR	84h
05h	PORTA	TRISA	85h
06h	PORTB	TRISB	86h
07h			87h
08h			88h
09h			89h
0Ah	PCLATH	PCLATH	8Ah
0Bh	INTCON	INTCON	8Bh
0Ch	PIR1	PIE1	8Ch
0Dh			8Dh
0Eh		PCON	8Eh
0Fh			8Fh
10h			90h
11h			91h
12h			92h
13h			93h
14h			94h
15h			95h
16h			96h
17h			97h
18h			98h
19h			99h
1Ah			9Ah
1Bh			9Bh
1Ch			9Ch
1Dh			9Dh
1Eh			9Eh
1Fh	CMCON	VRCON	9Fh
20h	General Purpose Register	General Purpose Register	A0h
			BFh
			C0h
6Fh			F0h
70h	General Purpose Register	Accesses 70h-7Fh	F0h
7Fh			FFh
Bank 0		Bank 1	

☐ Unimplemented data memory locations, read as '0'.
Note 1: Not a physical register.

5.0 I/O PORTS

The PIC16C62X have two ports, PORTA and PORTB. Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

5.1 PORTA and TRISA Registers

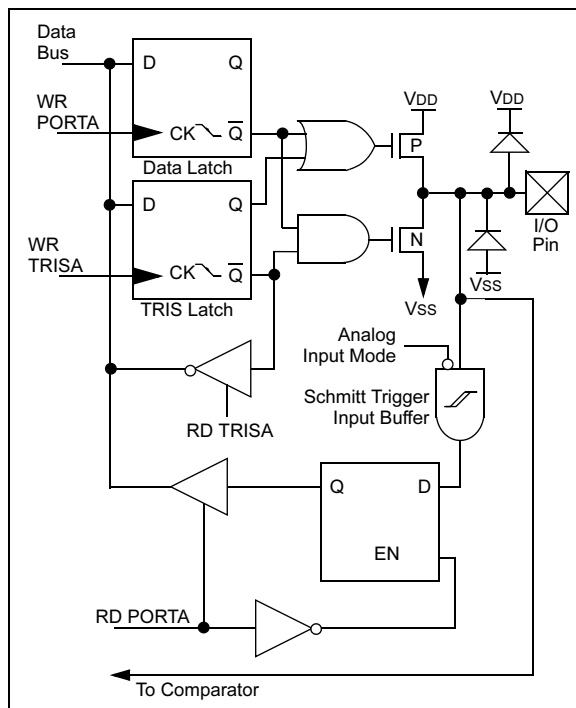
PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers), which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

The PORTA pins are multiplexed with comparator and voltage reference functions. The operation of these pins are selected by control bits in the CMCON (comparator control register) register and the VRCON (voltage reference control register) register. When selected as a comparator input, these pins will read as '0's.

FIGURE 5-1: BLOCK DIAGRAM OF RA1:RA0 PINS



Note: On RESET, the TRISA register is set to all inputs. The digital inputs are disabled and the comparator inputs are forced to ground to reduce excess current consumption.

TRISA controls the direction of the RA pins, even when they are being used as comparator inputs. The user must make sure to keep the pins configured as inputs when using them as comparator inputs.

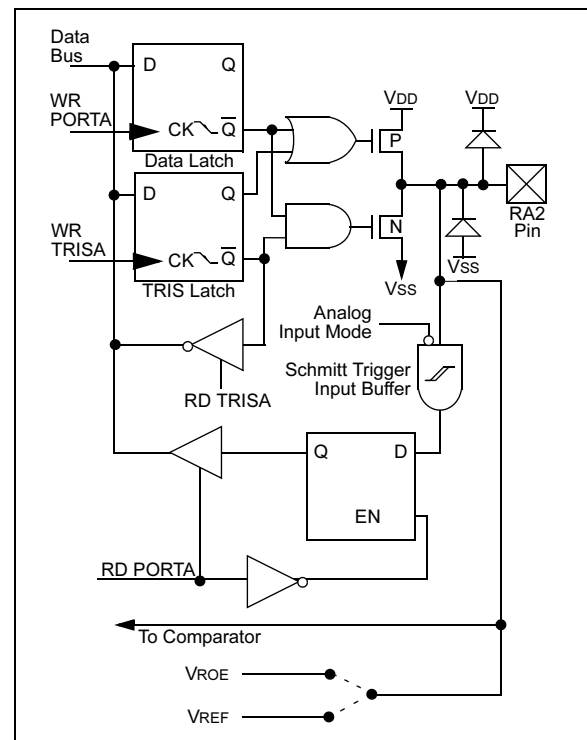
The RA2 pin will also function as the output for the voltage reference. When in this mode, the VREF pin is a very high impedance output and must be buffered prior to any external load. The user must configure TRISA<2> bit as an input and use high impedance loads.

In one of the Comparator modes defined by the CMCON register, pins RA3 and RA4 become outputs of the comparators. The TRISA<4:3> bits must be cleared to enable outputs to use this function.

EXAMPLE 5-1: INITIALIZING PORTA

```
CLRF    PORTA      ;Initialize PORTA by setting
                   ;output data latches
MOVLW   0X07       ;Turn comparators off and
MOVWF   CMCON      ;enable pins for I/O
                   ;functions
BSF     STATUS, RP0 ;Select Bank1
MOVLW   0x1F       ;Value used to initialize
                   ;data direction
MOVWF   TRISA      ;Set RA<4:0> as inputs
                   ;TRISA<7:5> are always
                   ;read as '0'.
```

FIGURE 5-2: BLOCK DIAGRAM OF RA2 PIN



7.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RA0 through RA3 pins. The On-Chip Voltage Reference (Section 8.0) can also be an input to the comparators.

The CMCON register, shown in Register 7-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 7-1.

REGISTER 7-1: CMCON REGISTER (ADDRESS 1Fh)

R-0	R-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT**: Comparator 2 output

1 = C2 VIN+ > C2 VIN-

0 = C2 VIN+ < C2 VIN-

bit 6 **C1OUT**: Comparator 1 output

1 = C1 VIN+ > C1 VIN-

0 = C1 VIN+ < C1 VIN-

bit 5-4 **Unimplemented**: Read as '0'

bit 3 **CIS**: Comparator Input Switch

When CM<2:0> = 001:

1 = C1 VIN- connects to RA3

0 = C1 VIN- connects to RA0

When CM<2:0> = 010:

1 = C1 VIN- connects to RA3

C2 VIN- connects to RA2

0 = C1 VIN- connects to RA0

C2 VIN- connects to RA1

bit 2-0 **CM<2:0>**: Comparator mode.

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

- n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSS with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at VDD or VSS for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note: It should be noted that a RESET generated by a WDT time-out does not drive MCLR pin low.

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked. $\overline{TO}$ bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

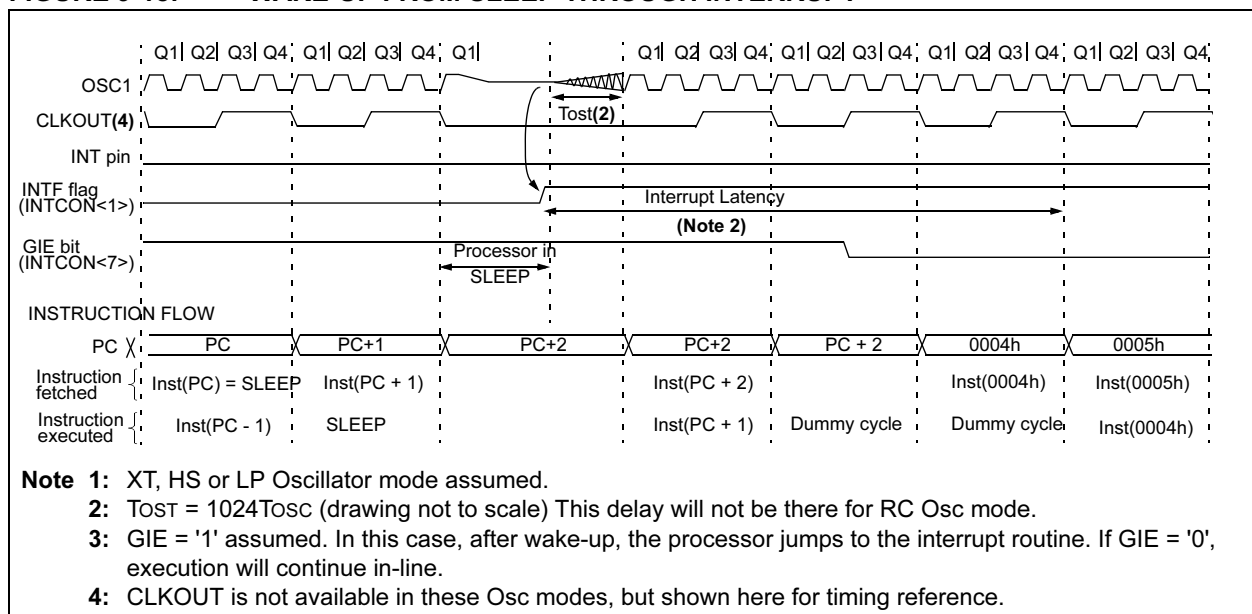
9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

1. External RESET input on MCLR pin
2. Watchdog Timer Wake-up (if WDT was enabled)
3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT



10.0 INSTRUCTION SET SUMMARY

Each PIC16C62X instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C62X instruction set summary in Table 10-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination either the W register or the specified register file location
[]	Options
()	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 10-1 lists the instructions recognized by the MPASM™ assembler.

Figure 10-1 shows the three general formats that the instructions can have.

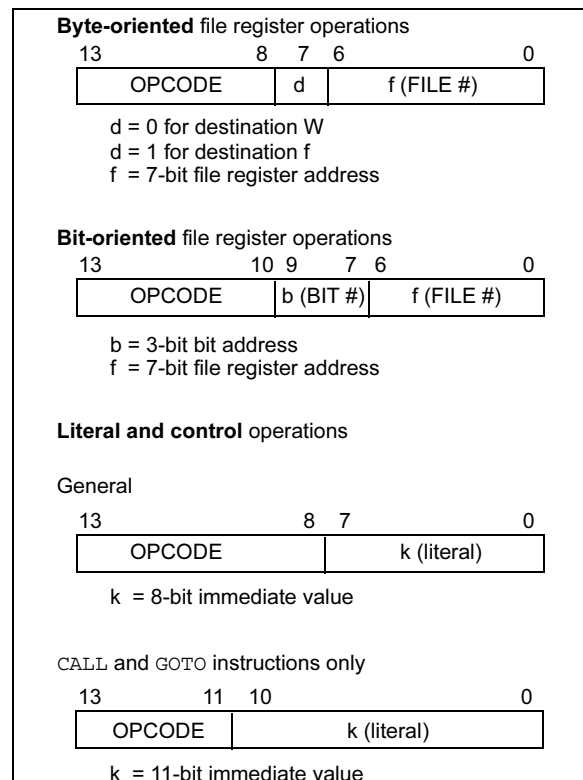
Note: To maintain upward compatibility with future PICmicro® products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



PIC16C62X

INCFSZ Increment f, Skip if 0

Syntax: `[label] INCFSZ f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(f) + 1 \rightarrow (\text{dest})$, skip if result = 0

Status Affected: None

Encoding:

00	1111	dfff	ffff
----	------	------	------

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
 If the result is 0, the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```

HERE      INCFSZ    CNT, 1
          GOTO      LOOP
CONTINUE  .
          .
          .
    
```

Before Instruction
 PC = address HERE

After Instruction
 CNT = CNT + 1
 if CNT= 0,
 PC = address CONTINUE
 if CNT≠ 0,
 PC = address HERE +1

IORLW Inclusive OR Literal with W

Syntax: `[label] IORLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) .OR. k \rightarrow (W)$

Status Affected: Z

Encoding:

11	1000	kkkk	kkkk
----	------	------	------

Description: The contents of the W register is OR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example

```

IORLW    0x35
    
```

Before Instruction
 W = 0x9A

After Instruction
 W = 0xBF
 Z = 1

IORWF Inclusive OR W with f

Syntax: `[label] IORWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .OR. (f) \rightarrow (\text{dest})$

Status Affected: $\bar{Z}$

Encoding:

00	0100	dfff	ffff
----	------	------	------

Description: Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```

IORWF          RESULT, 0
    
```

Before Instruction
 RESULT = 0x13
 W = 0x91

After Instruction
 RESULT = 0x13
 W = 0x93
 Z = 1

MOVLW Move Literal to W

Syntax: `[label] MOVLW k`

Operands: $0 \leq k \leq 255$

Operation: $k \rightarrow (W)$

Status Affected: None

Encoding:

11	00xx	kkkk	kkkk
----	------	------	------

Description: The eight bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.

Words: 1

Cycles: 1

Example

```

MOVLW    0x5A
    
```

After Instruction
 W = 0x5A

11.20 PICDEM 18R PIC18C601/801 Demonstration Board

The PICDEM 18R demonstration board serves to assist development of the PIC18C601/801 family of Microchip microcontrollers. It provides hardware implementation of both 8-bit Multiplexed/De-multiplexed and 16-bit Memory modes. The board includes 2 Mb external FLASH memory and 128 Kb SRAM memory, as well as serial EEPROM, allowing access to the wide range of memory types supported by the PIC18C601/801.

11.21 PICDEM LIN PIC16C43X Demonstration Board

The powerful LIN hardware and software kit includes a series of boards and three PICmicro microcontrollers. The small footprint PIC16C432 and PIC16C433 are used as slaves in the LIN communication and feature on-board LIN transceivers. A PIC16F874 FLASH microcontroller serves as the master. All three microcontrollers are programmed with firmware to provide LIN bus communication.

11.22 PICKit™ 1 FLASH Starter Kit

A complete "development system in a box", the PICKit FLASH Starter Kit includes a convenient multi-section board for programming, evaluation, and development of 8/14-pin FLASH PIC® microcontrollers. Powered via USB, the board operates under a simple Windows GUI. The PICKit 1 Starter Kit includes the user's guide (on CD ROM), PICKit 1 tutorial software and code for various applications. Also included are MPLAB® IDE (Integrated Development Environment) software, software and hardware "Tips 'n Tricks for 8-pin FLASH PIC® Microcontrollers" Handbook and a USB Interface Cable. Supports all current 8/14-pin FLASH PIC microcontrollers, as well as many future planned devices.

11.23 PICDEM USB PIC16C7X5 Demonstration Board

The PICDEM USB Demonstration Board shows off the capabilities of the PIC16C745 and PIC16C765 USB microcontrollers. This board provides the basis for future USB products.

11.24 Evaluation and Programming Tools

In addition to the PICDEM series of circuits, Microchip has a line of evaluation kits and demonstration software for these products.

- KEELOQ evaluation and programming tools for Microchip's HCS Secure Data Products
- CAN developers kit for automotive network applications
- Analog design boards and filter design software
- PowerSmart battery charging evaluation/calibration kits
- IrDA® development kit
- microID development and rLab™ development software
- SEEVAL® designer kit for memory evaluation and endurance calculations
- PICDEM MSC demo boards for Switching mode power supply, high power IR driver, delta sigma ADC, and flow rate sensor

Check the Microchip web page and the latest Product Line Card for the complete list of demonstration and evaluation kits.

PIC16C62X

FIGURE 12-5: PIC16LC620A/LC621A/LC622A VOLTAGE-FREQUENCY GRAPH, $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$

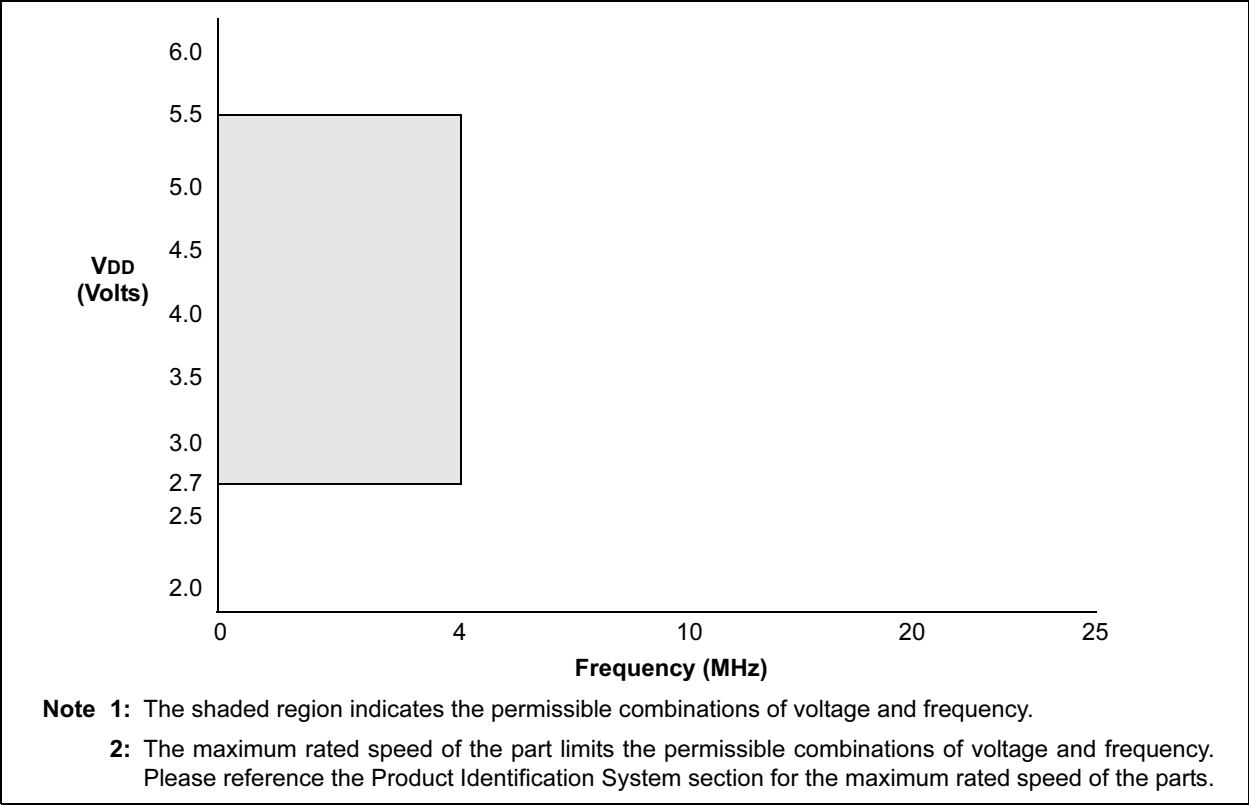
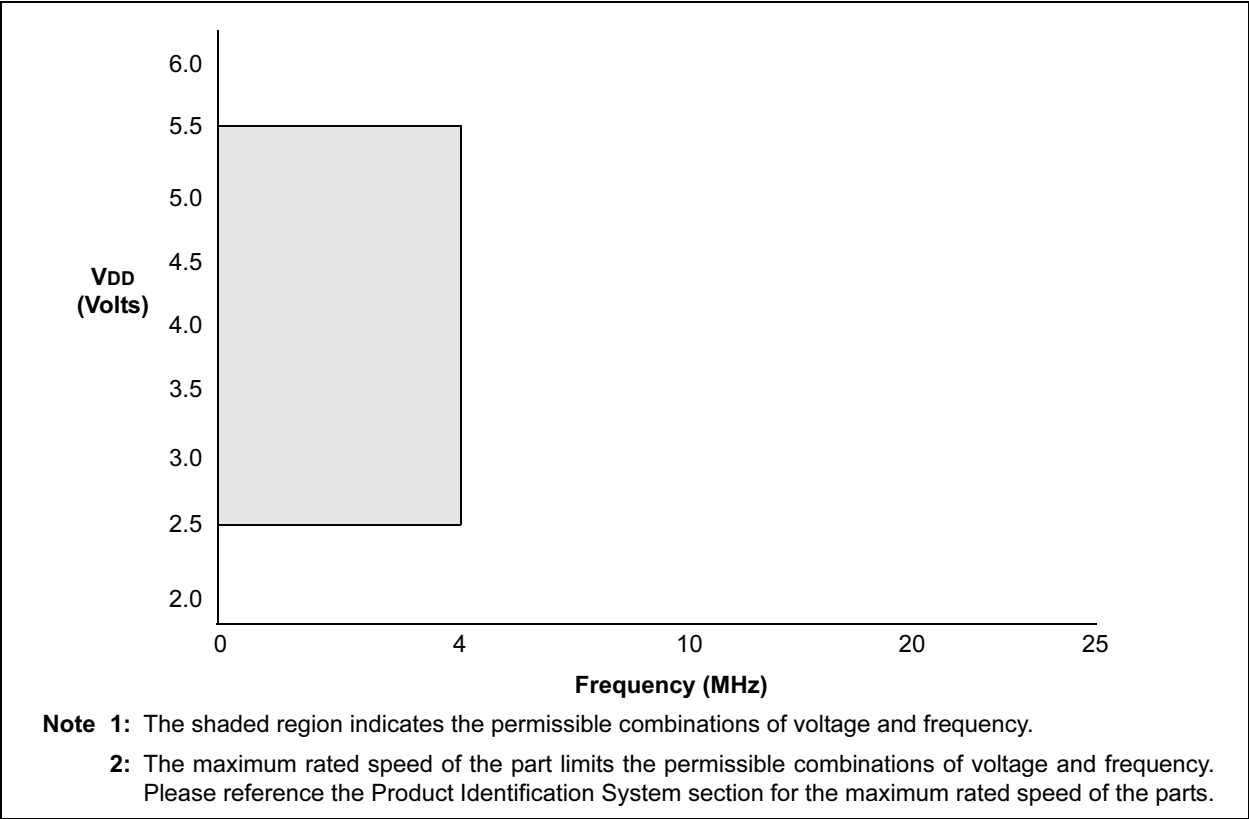


FIGURE 12-6: PIC16LC620A/LC621A/LC622A VOLTAGE-FREQUENCY GRAPH, $0^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$



12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16LC62X		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range is the PIC16C62X range.					
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	20	μA	$V_{DD}=4.0\text{V}$ (125°C)
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 4.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 4.0\text{V}$
D022	ΔI_{WDT}	WDT Current ⁽⁵⁾	—	6.0	15	μA	$V_{DD}=3.0\text{V}$
D022A	ΔI_{BOR}	Brown-out Reset Current ⁽⁵⁾	—	350	425	μA	BOD enabled, $V_{DD} = 5.0\text{V}$
D023	ΔI_{COMP}	Comparator Current for each Comparator ⁽⁵⁾	—	—	100	μA	$V_{DD} = 3.0\text{V}$
D023A	ΔI_{VREF}	VREF Current ⁽⁵⁾	—	—	300	μA	$V_{DD} = 3.0\text{V}$
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	kHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all I_{DD} measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to V_{DD} ,

MCLR = V_{DD} ; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to V_{DD} or V_{SS} .

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in k Ω .

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base I_{DD} or I_{PD} measurement.

PIC16C62X

PIC16CR62XA-04 PIC16CR62XA-20			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LCR62XA-04			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: $I_r = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

PIC16C62X

12.4 DC Characteristics: PIC16C62X/C62XA/CR62XA (Commercial, Industrial, Extended) PIC16LC62X/LC62XA/LCR62XA (Commercial, Industrial, Extended)

PIC16C62X/C62XA/CR62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
PIC16LC62X/LC62XA/LCR62XA			Standard Operating Conditions (unless otherwise stated)				
			Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial and $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial and $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D030 D031 D032 D033	V _{IL}	Input Low Voltage					
		I/O ports					
		with TTL buffer	V _{SS}	—	0.8V 0.15 V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	V _{SS}	—	0.2 V _{DD}	V	
		$\overline{\text{MCLR}}$, RA4/T0CKI, OSC1 (in RC mode)	V _{SS}	—	0.2 V _{DD}	V	(Note 1)
D033		OSC1 (in XT and HS)	V _{SS}	—	0.3 V _{DD}	V	
		OSC1 (in LP)	V _{SS}	—	0.6 V _{DD} - 1.0	V	
D030 D031 D032 D033	V _{IL}	Input Low Voltage					
		I/O ports					
		with TTL buffer	V _{SS}	—	0.8V 0.15 V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	V _{SS}	—	0.2 V _{DD}	V	
		$\overline{\text{MCLR}}$, RA4/T0CKI, OSC1 (in RC mode)	V _{SS}	—	0.2 V _{DD}	V	(Note 1)
D033		OSC1 (in XT and HS)	V _{SS}	—	0.3 V _{DD}	V	
		OSC1 (in LP)	V _{SS}	—	0.6 V _{DD} - 1.0	V	
D040 D041 D042 D043 D043A	V _{IH}	Input High Voltage					
		I/O ports					
		with TTL buffer	2.0V 0.25 V _{DD} + 0.8V	—	V _{DD} V _{DD}	V	V _{DD} = 4.5V to 5.5V otherwise
		with Schmitt Trigger input	0.8 V _{DD}	—	V _{DD}	V	
		$\overline{\text{MCLR}}$ RA4/T0CKI	0.8 V _{DD}	—	V _{DD}	V	
D043 D043A		OSC1 (XT, HS and LP)	0.7 V _{DD}	—	V _{DD}	V	
		OSC1 (in RC mode)	0.9 V _{DD}	—	V _{DD}	V	(Note 1)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16C62X(A) be driven with external clock in RC mode.
- 2:** The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3:** Negative current is defined as coming out of the pin.

FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

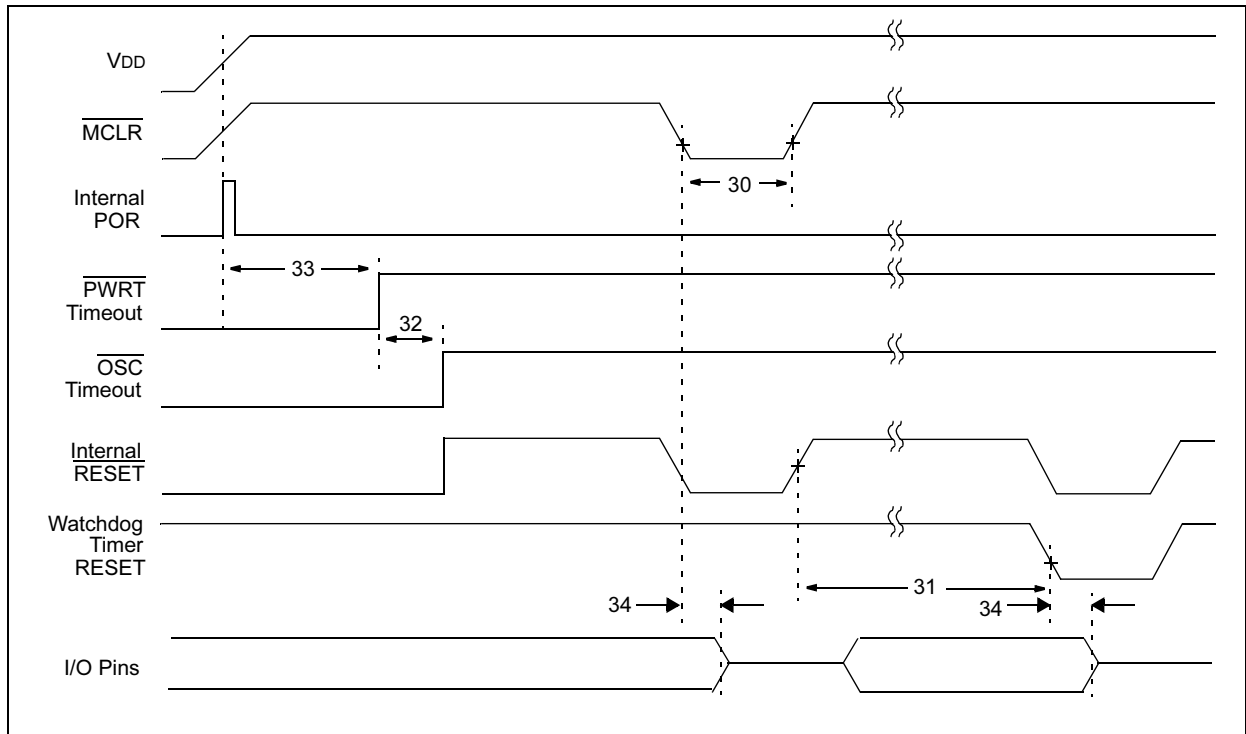


FIGURE 12-15: BROWN-OUT RESET TIMING

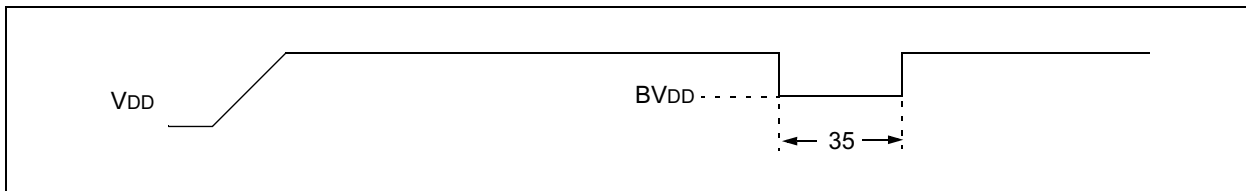


TABLE 12-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

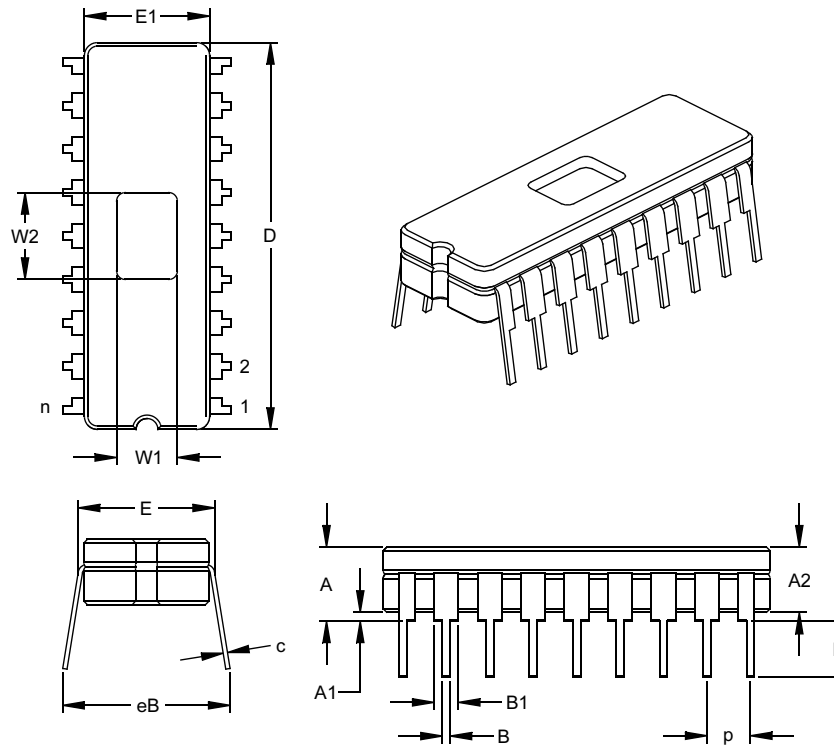
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	Tmcl	MCLR Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	TIOZ	I/O hi-impedance from MCLR low	—	—	2.0	μs	
35	TBOR	Brown-out Reset Pulse Width	100*	—	—	μs	3.7V ≤ VDD ≤ 4.3V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

14.0 PACKAGING INFORMATION

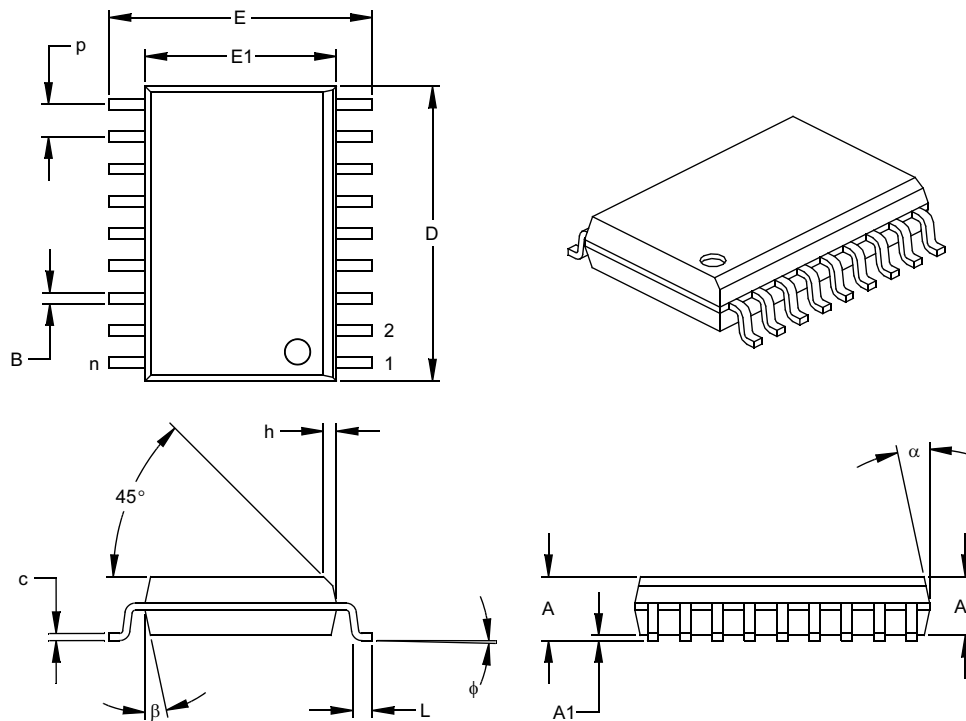
18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	§ eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
 § Significant Characteristic
 JEDEC Equivalent: MO-036
 Drawing No. C04-010

18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

PIC16C62X

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